



Material Content Data Sheet



Sales Product Name		BSC130P03LS G		Issued		29. August 2013		
MA#		MA000621176						
Package		PG-TDSON-8-3		Weight*		103.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.447	2.37	2.37	23693	23693
leadframe	non noble metal	iron	7439-89-6	0.038	0.04		366	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		110	
	non noble metal	copper	7440-50-8	37.762	36.57	36.62	365696	366172
wire	noble metal	gold	7440-57-5	0.936	0.91	0.91	9060	9060
encapsulation	organic material	carbon black	1333-86-4	0.094	0.09		907	
	plastics	epoxy resin	-	6.653	6.44		64431	
	inorganic material	silicondioxide	60676-86-0	40.106	38.85	45.38	388403	453741
leadfinish	non noble metal	tin	7440-31-5	1.452	1.41	1.41	14058	14058
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1603	1603
solder	non noble metal	tin	7440-31-5	0.045	0.04		438	
	noble metal	silver	7440-22-4	0.057	0.05		548	
	non noble metal	lead	7439-92-1	2.160	2.09	2.18	20917	21903
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		33	
	non noble metal	iron	7439-89-6	0.011	0.01		110	
	non noble metal	copper	7440-50-8	11.320	10.96	10.97	109627	109770
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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